



Material Content Data Sheet



Sales Product Name		BC 848BW H6327		Issued		2. August 2018			
MA#		MA000854912							
Package		PG-SOT323-3-1		Weight*		5.96 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		5		
	noble metal	gold	7440-57-5	0.003	0.05		493		
	inorganic material	silicon	7440-21-3	0.025	0.42	0.47	4207	4705	
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		88		
	non noble metal	titanium	7440-32-6	0.003	0.04		441		
	non noble metal	chromium	7440-47-3	0.008	0.13		1324		
	non noble metal	copper	7440-50-8	2.617	43.95	44.13	439446	441299	
wire	non noble metal	copper	7440-50-8	0.006	0.10	0.10	973	973	
encapsulation	organic material	carbon black	1333-86-4	0.032	0.53		5291		
	plastics	epoxy resin	-	0.677	11.37		113748		
	inorganic material	silicondioxide	60676-86-0	2.442	41.00	52.90	410020	529059	
leadfinish	non noble metal	tin	7440-31-5	0.133	2.23	2.23	22283	22283	
plating	noble metal	silver	7440-22-4	0.010	0.17	0.17	1681	1681	
*deviation	< 10%				Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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